

Notice of References Cited	Application/Control No. 10/708,399		Applicant(s)/Patent Under Reexamination LIN ET AL.	
	Examiner Ryan M. Stiglic		Art Unit 2112	Page 1 of 1

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*	B	US-6,813,689 B2	11-2004	Baxter, III, William Frederick	711/114
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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